

IPT ST TP2005 S GAP FILLER*Technical Data Sheet*

TP 2005 S is a modern thermally conductive composite based on silicone, featuring exceptional thermal conductivity of 2.0 W/m·K. The composite is flexible and perfectly conforms to the surface to which it is applied. The thermal pad is available in any desired shape and size.

TECHNICAL SPECIFICATION	
Composite carrier	Silicone
Colour	Grey
Thermal Conductivity ASTM D5470	2.0 W/m·K
Hardness [Shore OO]	40
Performance temperature range	-40°C - +200°C
Dielectric breakdown	5 kV
Flammability [UL94]	V-0
Liner	Transparent
Specific Gravity	2700 kg/m ³
SIZE	
Thickness	0.5 mm
Length	Up to 400 mm
Width	Up to 200 mm

STORAGE:

Thermal pad IPT ST - TP2005 S should be stored in its original packaging, in a dry, clean, and covered area.

- o Storage temperature for the thermopad: 10°C to 30°C
- o Relative humidity for storage: ~55%
- o Shelf life of the thermopad before application: 24 months

APPLICATION:

- o The thermal pad should be applied at room temperature, between 20°C and 22°C.
- o Optimal performance is achieved when the thermopad is applied to a dry, degreased surface

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The above technical information is presented based on the average laboratory tests and can not be used as binding technical data for design purposes, they should not be used as a basis for granting the guarantee. The user is fully responsible for the decision to use the product and for its installation. Before using it is recommended to analyse the product features considering the type of combined materials, the state of its surface and application conditions.